

DECLARATION FOR PATENT APPLICATION

As a below named inventor, I declare:
that I verily believe myself to be the original, first and sole (if only one individual inventor is listed below) or an original, first and joint inventor (if more than one individual inventor is listed below) of the invention in

SEMICONDUCTOR PACKAGE AND METHOD OF FABRICATING THE SAME

the specification of which is attached hereto unless the following box is checked.

☐ was filed on _____ as United States Application
or PCT International Application No. _____, and
was amended on _____ (if applicable).

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information of which is material to patentability as defined in 37 CFR 1.56.

I hereby claim foreign priority benefits under 35 U.S.C. 119(a)-(d) or 365 (b) of any foreign application(s) for patent or inventor's certificate, or 35 U.S.C. 365(a) of any PCT International application which designated at least one country other than the United States, listed below and have also identified below any foreign application for patent or inventor's certificate, or PCT International application having a filing date before that of the application on which priority is claimed:

<u>Country</u>	<u>Category</u>	<u>Application No.</u>	<u>Filing Date</u>	<u>Priority Claim</u>
Japan	Patent	2002-274807	September 20, 2002	Yes

I hereby appoint the registrants of Frishauf, Holtz, Goodman & Chick, P.C., 767 Third Avenue - 25th Floor, New York, N.Y. 10017-2023, Customer No. 01933, or any one of them. Send correspondence to Frishauf, Holtz, Goodman & Chick, P.C., 767 Third Avenue - 25th Floor, New York, N.Y. 10017-2023, Telephone No. (212) 319-4900.

I declare further that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

I declare further that my citizenship, residence and mailing address are as stated below next to my name:

Inventor: (Signature)

Date _____

Residence and mailing address

Date: September 4, 2003

Citizen of: Japan

1-9-1-610, Kuboyamacho,
Hachioji-shi, Tokyo, Japan

Hiroyasu Jobetto

Date:

Citizen of: Japan

Date:

Citizen of: Japan

Date:

Citizen of: Japan

Date:

Citizen of: Japan

Date:

Citizen of: Japan

Date:

Citizen of: Japan

Date:

Citizen of: Japan